

Press Release

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MicroTCA

Subrack including backplane

The open MicroTCA standard is basically an extension of the 19" standard and defines subrack dimensions, power modules, the MicroTCA Carrier Hub (MCH), the Shelf Management and the use of AMC modules. Thereby, apart from complete MicroTCA systems, subrack solutions conforming to the standard can also be configured.

Based on the MicroTCA standard Schroff has not only developed a product range with complete systems but also an entire subrack range. These subracks, which are constructed from only a few components in 3 U for Single AMC modules and in 4 U for Double AMC modules, consist of two side panels, cover and base plate as well as rear panel made from steel. The hexagonal perforation in the cover and base plate guarantees maximum air circulation and stability at the same time. M3 threads are already integrated into the cover and base plate. The totally shielded subracks are available in 19", metric as well as in smaller dimensions for a small number of AMC modules as Cube or Pico subracks. All of these subracks have a depth of 200 mm. The grid of the MicroTCA subrack is determined at 1 HP (5.08 mm), which means that in a spacing of 1 HP the corresponding plastic board guides can be clipped into the cover or base plate of the subracks, retrospectively. The die-cast part which is fixed at the bottom to the red board guides enables the locking of the inserted board. The board guides for the top are green and are equipped with an ESD clip, the bottom versions are red. All three defined module widths, Compact (3 HP), Mid-size (4 HP) and Full-size (6 HP) can be used.

Further information:

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Schroff offers suitable backplanes in Star or Dual Star topology for all subracks which support all defined protocols such as Gigabit-Ethernet, PCI Express, Rapid I/O, serialATA etc. Furthermore specific backplane layouts are available at request. Through the open standard, the modularity and the scalability there will be many customer specific versions. With the fan units and other accessories which are all available from Schroff these simple subracks can easily be extended to a MicroTCA complete system.

Picture caption: Simple MicroTCA subrack solutions with backplane

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